



(0.50 mm) .0197"

QTH-060-07-F-D-A

QTH-030-01-L-D-A

QTH-090-01-C-D-A

QTH SERIES

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTH

Insulator Material:
Liquid Crystal Polymer
Terminal Material:
Phosphor Bronze
Plating: Au or Sn over 50µ" (1.27 µm) Ni
Current Rating:
Contact:
2 A per pin
(1 pin powered per row)
Ground Plane:
25 A per ground plane
(1 ground plane powered)

Operating Temp Range:
-55°C to +125°C
Voltage Rating:
125 VAC (5 mm Stack Height)
Max Cycles: 100
RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (030-060)
(0.15 mm) .006" max (090)
Board Stacking:
For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
 - 30µ" (0.76 µm) Gold (Specify -H plating for Data Rate cable mating applications.)
 - Edge Mount & Guide Posts
 - 80 (-DP), 120, 150 positions per row
 - Retention Option
- Contact Samtec.

Board Mates:
QSH

Cable Mates:
HQCD, HQDP
(See Also Available note)



QTH/QSH 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	9.5 GHz / 19 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	10.5 GHz / 21 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps	16.5 GHz / 33 Gbps

*Performance data includes effects of a non-optimized PCB.

**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?QTH or contact sig@samtec.com

Integral metal plane for power or ground

Standard Stack Heights from 5 mm to 25 mm

Protocols Supported

100 GbE
Hypertransport™
XAUI
PCI Express®
SATA
InfiniBand™

Download app notes at
www.samtec.com/appnote
Contact SIG @ samtec.com
for questions on protocols

Finalinch
CERTIFIED

28+
Gbps

QTH — **PINS PER ROW NO. OF PAIRS** — **LEAD STYLE** — **PLATING OPTION** — **TYPE** — **A** — **OTHER OPTION**

—030, —060, —090
(60 total pins per bank = -D)

—020, —040, —060
(20 pairs per bank = -D-DP)

Specify
LEAD
STYLE
from
chart

—F
= Gold Flash on
Signal Pins and
Ground Plane,
Matte Tin on tails

—L
= 10µ" (0.25 µm)
Gold on Signal Pins
and Ground Plane,
Matte Tin on tails

—C*
= Electro-Polished
Selective
50µ" (1.27 µm) min Au
over 150µ" (3.81 µm)
Ni on Signal Pins in
contact area,
10µ" (0.25 µm) min Au
over 50µ" (1.27 µm)
Ni on Ground Plane
in contact area,
Matte Tin over 50µ"
(1.27 µm) min Ni
on all solder tails

—D
= Single-Ended

—D-DP
= Differential Pair
(-01 only)

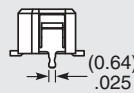
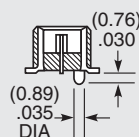
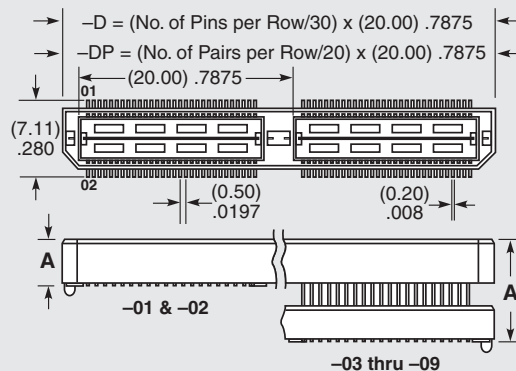
QTH LEAD STYLE	A	HEIGHT WITH QSH*
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315
-03	(10.27) .404	(11.00) .433
-04	(15.25) .600	(16.00) .630
-05	(18.26) .718	(19.00) .748
-07	(24.24) .954	(25.00) .984
-09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height.

—K
= (7.00 mm)
.275" DIA
Polyimide
film Pick &
Place Pad
(N/A with -05 &
-07 lead style)

—TR
= Tape & Reel
(-090 positions
maximum)

—L
= Latching
Option
(-01 lead
style only)
(N/A on
-060 (-D-DP)
& -090)



*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

OTHER SOLUTIONS

- Board Spacing Standoffs. See SO Series.